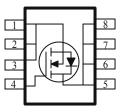
## N-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low r<sub>DS(on)</sub> provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOIC-8 saves board space
- Fast switching speed
- High performance trench technology

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	$r_{\mathrm{DS(on)}} m(\Omega)$	$r_{DS(on)} m(\Omega)$ $I_D(A)$	
30	$13.5 @ V_{GS} = 10V$	13	
	$20 @ V_{GS} = 4.5V$	11	





ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	Limit	Units		
Drain-Source Voltage		V <sub>DS</sub>	30	V		
Gate-Source Voltage		V <sub>GS</sub>	±20	v		
	$T_A=25^{\circ}C$		±13			
Continuous Drain Current <sup>a</sup>	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	ID	±11	А		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	±50			
Continuous Source Current (Diode Conduction) <sup>a</sup>		Is	2.3	Α		
	$T_A=25^{\circ}C$	D	3.1	W		
Power Dissipation <sup>a</sup>	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	LD	2.2	vv		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case <sup>a</sup>	t <= 5 sec	$R_{\theta JC}$	25	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	t <= 5 sec	$R_{\theta JA}$	50	°C/W	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

Parameter	Sh al	<b>Test Conditions</b>	Limits			Unit
rarameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Static						
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \text{ uA}$	1			V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = 20 V$			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 24 V, V_{GS} = 0 V$			1	uA
	255	$V_{DS} = 24 V, V_{GS} = 0 V, T_J = 55^{\circ}C$			25	
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	20			Α
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$			13.5	mΩ
Drain-Source On-Resistance		$V_{GS} = 4.5 \text{ V}, I_D = 8 \text{ A}$			20	
Forward Tranconductance <sup>A</sup>	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$		40		S
Diode Forward Voltage	V <sub>SD</sub>	$I_{\rm S} = 2.3$ A, $V_{\rm GS} = 0$ V		0.7		V
Dynamic <sup>b</sup>						
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$ $I_D = 10 \text{ A}$		12.5		nC
Gate-Source Charge	Q <sub>gs</sub>			2.6		
Gate-Drain Charge	Q <sub>gd</sub>			4.6		
Input Capacitance	C <sub>iss</sub>	$V_{DS} = 15 V, V_{GS} = 0 V,$ f = 1MHz		1191		pF
Output Capacitance	C <sub>oss</sub>			412		
Reverse Transfer Capacitance	C <sub>rss</sub>			160		
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{\rm DD}$ = 25 V, $R_{\rm L}$ = 25 $\Omega$ , ${\rm Id}$ = 1 A, $V_{\rm GEN}$ = 10 V		20		nS
Rise Time	t <sub>r</sub>			9		
Turn-Off Delay Time	t <sub>d(off)</sub>			70		
Fall-Time	t <sub>f</sub>			20		

Notes

a. Pulse test:  $PW \le 300$ us duty cycle  $\le 2\%$ .

b. Guaranteed by design, not subject to production testing.

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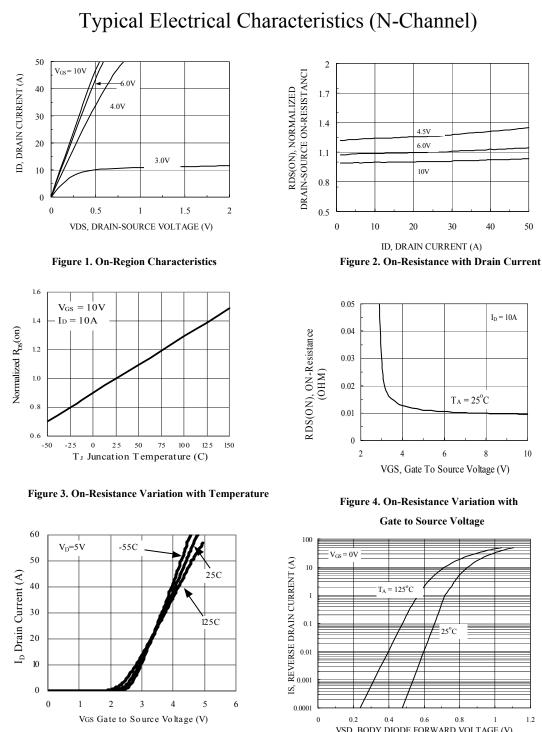


Figure 5. Transfer Characteristics

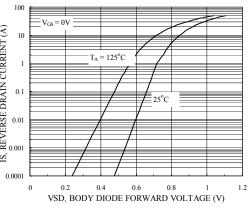
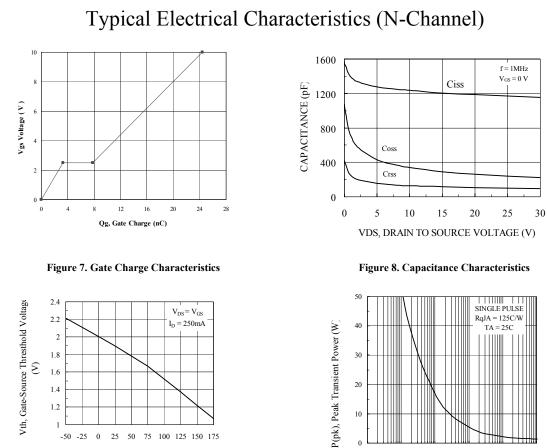


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature



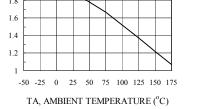
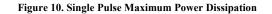


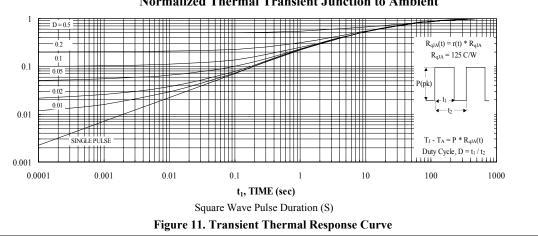
Figure 9. Threshold Vs Ambient Temperature



0.1

10

1 t1, TIME (sec) 100



Normalized Thermal Transient Junction to Ambient

10

0

0.001

0.01

